

**REMARKS**

By this Supplemental Amendment, new claims 40-41 have been added, leaving claims 1-41 pending.

Claims 40 and 41 each depend from claim 1. Claim 40 recites that "the surface of said second substrate is flat." Support for this feature is provided, for example, in Fig. 1c, showing a flat lower surface of wafer 3. In contrast, the alleged "second substrate" (i.e., preform 114) of Budinski is round.

Claim 41 recites that "a process chamber pressure acts upon the surface of said second substrate which is turned away from said first substrate throughout the annealing and the flow of the glass into the recesses of said structured surface of said first substrate." Support for claim 41 is provided, for example, in claim 14 and at page 11, next-to-last paragraph of the specification. In contrast, in Budinski's method, the upper mold half 102 applies pressure to the preform 114 throughout the glass flow process so as to compact the preform and cause the glass flow to occur.

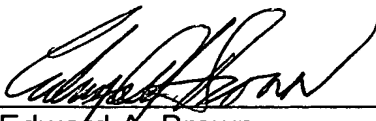
Accordingly, Budinski also fails to disclose or suggest the features recited in claims 40 and 41. Therefore, claims 40 and 41 also are patentable over Budinski.

For the reasons stated in the August 17 Amendment and the above-stated reasons, allowance of the application is respectfully requested. Should the Examiner have any questions regarding this Supplemental Amendment, Applicants' undersigned representative can be reached at the telephone number given below.

Respectfully submitted,

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